



Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
 [List multiple models if applicable.]

HP G62 Notebook PC

Name / Model #2

Name / Model #3

Name / Model #4

Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Motherboard, Touch pad	2
Batteries	All types including standard alkaline and lithium coin or button style batteries Coin cell battery, Battery pack	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps (LCD panel)	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0

Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Screwdriver	Type-cross #1 (JIS B 4633-1987)
Description #2	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassemble main battery
2. Disassemble ram door & hdd door
3. Dis-fasten BASE screw*21(M2.5*3,M2.5*5,M2.5*6.5)
4. Pull out hdd cable
5. Dis-fasten hdd screw*2(M2.5*5)
6. Disassemble HDD ASSY
7. Dis-fasten hdd bracket screw*4(M3*3.5)
8. Remove HDD
9. Pull out WLAN cables
10. Dis-fasten WLAN module screw*1(M2*3)
11. Remove WLAN module
12. Remove RAM module from Mainboard
13. Remove ODD ASSY
14. Remove ODD from ODD ASSY
15. Pull out Keyboard membrane
16. Remove Keyboard
17. Dis-fasten TOP screw*1(M2.5*5)
18. Pull out speaker cable
19. Pull out power FFC, Touchpad FFC & TP button FFC
20. Disassemble TOP ASSY
21. Dis-fasten speaker screw*3(M2.5*3)
22. Disassemble speaker
23. Pull out LCD cable, MIC cable, CCD cable, Bluetooth cable, ODD cable, Modem cable,DC cable & USB FFC
24. Dis-fasten Modem screw*2(M2*3)
25. Remove Modem module
26. Dis-fasten LCD ASSY screw*4(M2.5*6.5)
27. Disassemble LCD ASSY

28. Dis-fasten Mainboard & FAN module screw*3(M2.5*4)
29. Disassemble Mainboard
30. Dis-fasten fan screw*6
31. Remove FAN module
32. Disassemble CPU
33. Remove screw mylar*2
34. Dis-fasten LCD BEZEL screw*2(M2.5*3)
35. Disassemble LCD BEZEL
36. Dis-fasten hinge cover screw*2(M2.5*4)
37. Remove hinge cover*2
38. Dis-fasten hinge screw*8(M2.5*4)
39. Disassemble panel with hinge bracket
40. Dis-fasten hinge bracket screw*4(M2*3)
41. Remove hinge bracket
42. Pull out LCD cable

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

LCD panel disassembly process



